

## IGBT

High speed IGBT in Trench and Fieldstop technology  
recommended in combination with SiC Diode IDH15S120

## IGW25N120H3

1200V high speed switching series third generation

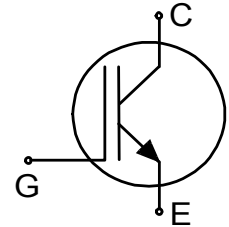
Data sheet

High speed IGBT in Trench and Fieldstop technology recommended in combination with SiC Diode IDH15S120

**Features:**

TRENCHSTOP™ technology offering

- best in class switching performance: less than 500µJ total switching losses achievable
- very low  $V_{CEsat}$
- low EMI
- maximum junction temperature 175°C
- qualified according to JEDEC for target applications
- Pb-free lead plating; RoHS compliant
- complete product spectrum and PSpice Models: <http://www.infineon.com/igbt/>



**Applications:**

- solar inverters
- uninterruptible power supplies
- welding converters
- converters with high switching frequency



**Package pin definition:**

- Pin 1 - gate
- Pin 2 & backside - collector
- Pin 3 - emitter



**Key Performance and Package Parameters**

Type	$V_{CE}$	$I_C$	$V_{CEsat}, T_{vj}=25^{\circ}C$	$T_{vjmax}$	Marking	Package
IGW25N120H3	1200V	25A	2.05V	175°C	G25H1203	PG-TO247-3



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**Maximum ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	1200	V
DC collector current, limited by $T_{vjmax}$ $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	$I_C$	50.0 25.0	A
Pulsed collector current, $t_p$ limited by $T_{vjmax}$	$I_{Cpuls}$	100.0	A
Turn off safe operating area $V_{CE} \leq 1200\text{V}$ , $T_{vj} \leq 175^\circ\text{C}$	-	100.0	A
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time $V_{GE} = 15.0\text{V}$ , $V_{CC} \leq 600\text{V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{s}$ $T_{vj} = 175^\circ\text{C}$	$t_{SC}$	10	$\mu\text{s}$
Power dissipation $T_C = 25^\circ\text{C}$ Power dissipation $T_C = 100^\circ\text{C}$	$P_{tot}$	326.0 156.0	W
Operating junction temperature	$T_{vj}$	-40...+175	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55...+150	$^\circ\text{C}$
Soldering temperature, wave soldering 1.6 mm (0.063 in.) from case for 10s		260	$^\circ\text{C}$
Mounting torque, M3 screw Maximum of mounting processes: 3	$M$	0.6	Nm

**Thermal Resistance**

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction - case	$R_{th(j-c)}$		0.46	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$		40	K/W

**Electrical Characteristic, at  $T_{vj} = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{V}$ , $I_C = 0.50\text{mA}$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CEsat}$	$V_{GE} = 15.0\text{V}$ , $I_C = 25.0\text{A}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	- - -	2.05 2.50 2.70	2.40 - -	V
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 0.85\text{mA}$ , $V_{CE} = V_{GE}$	5.0	5.8	6.5	V
Zero gate voltage collector current	$I_{CES}$	$V_{CE} = 1200\text{V}$ , $V_{GE} = 0\text{V}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	- -	- -	250.0 2500.0	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0\text{V}$ , $V_{GE} = 20\text{V}$	-	-	600	nA
Transconductance	$g_{fs}$	$V_{CE} = 20\text{V}$ , $I_C = 25.0\text{A}$	-	13.0	-	S

**Electrical Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Dynamic Characteristic</b>						
Input capacitance	$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	1430	-	pF
Output capacitance	$C_{oes}$		-	95	-	
Reverse transfer capacitance	$C_{res}$		-	75	-	
Gate charge	$Q_G$	$V_{CC} = 960\text{V}, I_C = 25.0\text{A}, V_{GE} = 15\text{V}$	-	115.0	-	nC
Short circuit collector current Max. 1000 short circuits Time between short circuits: $\geq 1.0\text{s}$	$I_{C(SC)}$	$V_{GE} = 15.0\text{V}, V_{CC} \leq 600\text{V}, t_{SC} \leq 10\mu\text{s}, T_{vj} = 175^{\circ}\text{C}$	-	87	-	A

**Switching Characteristic, Inductive Load**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

**IGBT Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$** 

Turn-on delay time	$t_{d(on)}$	$T_{vj} = 25^{\circ}\text{C}, V_{CC} = 600\text{V}, I_C = 25.0\text{A}, V_{GE} = 0.0/15.0\text{V}, r_G = 23.0\Omega, L\sigma = 80\text{nH}, C\sigma = 67\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include "tail" and diode (IKW25N120H3) reverse recovery.	-	27	-	ns
Rise time	$t_r$		-	41	-	ns
Turn-off delay time	$t_{d(off)}$		-	277	-	ns
Fall time	$t_f$		-	17	-	ns
Turn-on energy	$E_{on}$		-	1.80	-	mJ
Turn-off energy	$E_{off}$		-	0.85	-	mJ
Total switching energy	$E_{ts}$		-	2.65	-	mJ
Turn-on energy	$E_{on}$	$T_{vj} = 25^{\circ}\text{C}, V_{CC} = 800\text{V}, I_C = 10.0\text{A}, V_{GE} = 0.0/15.0\text{V}, r_G = 3.0\Omega, L\sigma = 80\text{nH}, C\sigma = 67\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include "tail" and diode (IDH15S120) reverse recovery.	-	0.08	-	mJ
Turn-off energy	$E_{off}$		-	0.27	-	mJ
Total switching energy	$E_{ts}$		-	0.35	-	mJ

**Switching Characteristic, Inductive Load**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic, at <math>T_{vj} = 175^{\circ}\text{C}</math></b>						
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 175^{\circ}\text{C}$ , $V_{CC} = 600\text{V}$ , $I_C = 25.0\text{A}$ , $V_{GE} = 0.0/15.0\text{V}$ , $r_G = 23.0\Omega$ , $L\sigma = 80\text{nH}$ , $C\sigma = 67\text{pF}$ $L\sigma$ , $C\sigma$ from Fig. E Energy losses include "tail" and diode (IKW25N120H3) reverse recovery.	-	26	-	ns
Rise time	$t_r$		-	35	-	ns
Turn-off delay time	$t_{d(off)}$		-	347	-	ns
Fall time	$t_f$		-	50	-	ns
Turn-on energy	$E_{on}$		-	2.60	-	mJ
Turn-off energy	$E_{off}$		-	1.70	-	mJ
Total switching energy	$E_{ts}$		-	4.30	-	mJ
Turn-on energy	$E_{on}$	$T_{vj} = 175^{\circ}\text{C}$ , $V_{CC} = 800\text{V}$ , $I_C = 10.0\text{A}$ , $V_{GE} = 0.0/15.0\text{V}$ , $r_G = 3.0\Omega$ , $L\sigma = 80\text{nH}$ , $C\sigma = 67\text{pF}$ $L\sigma$ , $C\sigma$ from Fig. E Energy losses include "tail" and diode (IDH15S120) reverse recovery.	-	0.10	-	mJ
Turn-off energy	$E_{off}$		-	0.62	-	mJ
Total switching energy	$E_{ts}$		-	0.72	-	mJ

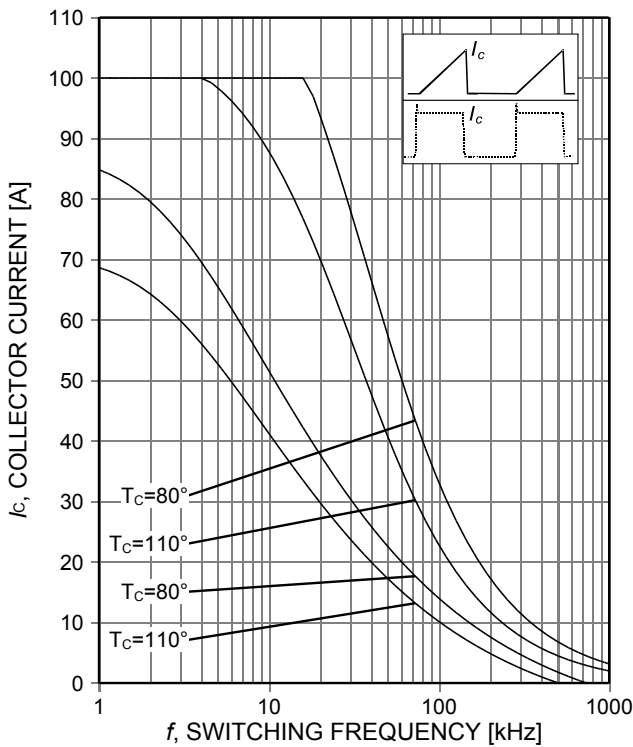


Figure 1. **Collector current as a function of switching frequency**  
 ( $T_j \leq 175^\circ\text{C}$ ,  $D=0.5$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $r_G=23\Omega$ )

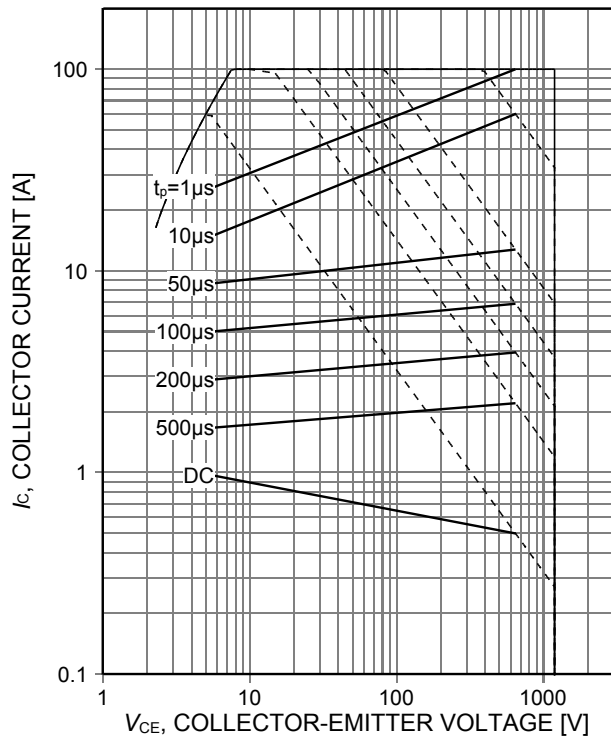


Figure 2. **Forward bias safe operating area**  
 ( $D=0$ ,  $T_C=25^\circ\text{C}$ ,  $T_j \leq 175^\circ\text{C}$ ;  $V_{GE}=15\text{V}$ )

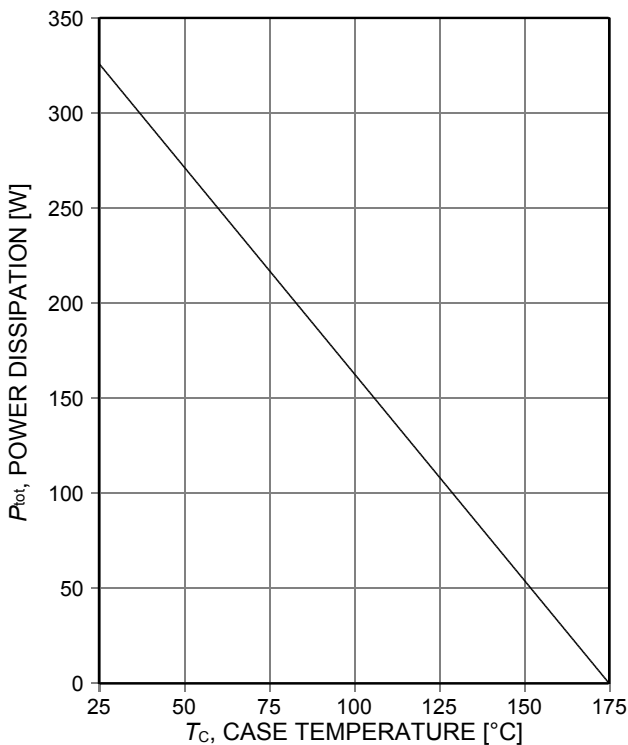


Figure 3. **Power dissipation as a function of case temperature**  
 ( $T_j \leq 175^\circ\text{C}$ )

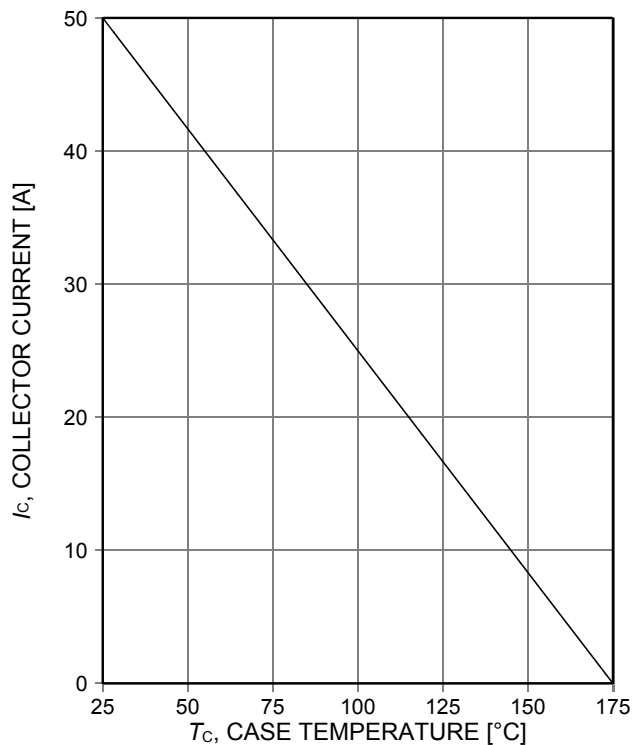


Figure 4. **Collector current as a function of case temperature**  
 ( $V_{GE} \geq 15\text{V}$ ,  $T_j \leq 175^\circ\text{C}$ )

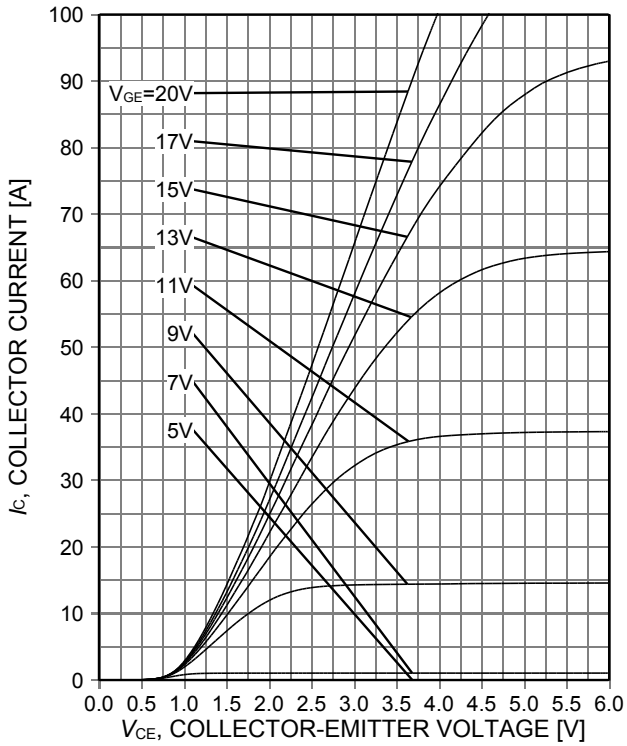


Figure 5. **Typical output characteristic**  
( $T_j=25^\circ\text{C}$ )

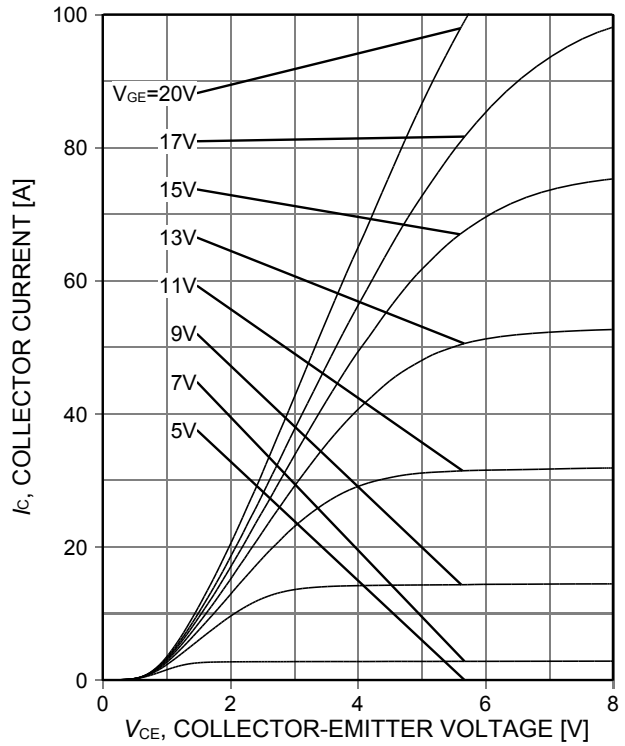


Figure 6. **Typical output characteristic**  
( $T_j=175^\circ\text{C}$ )

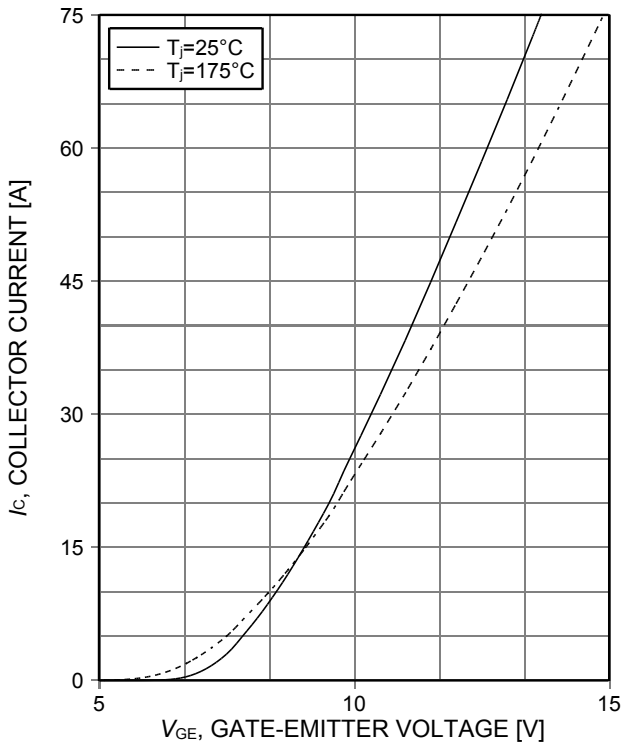


Figure 7. **Typical transfer characteristic**  
( $V_{CE}=20\text{V}$ )

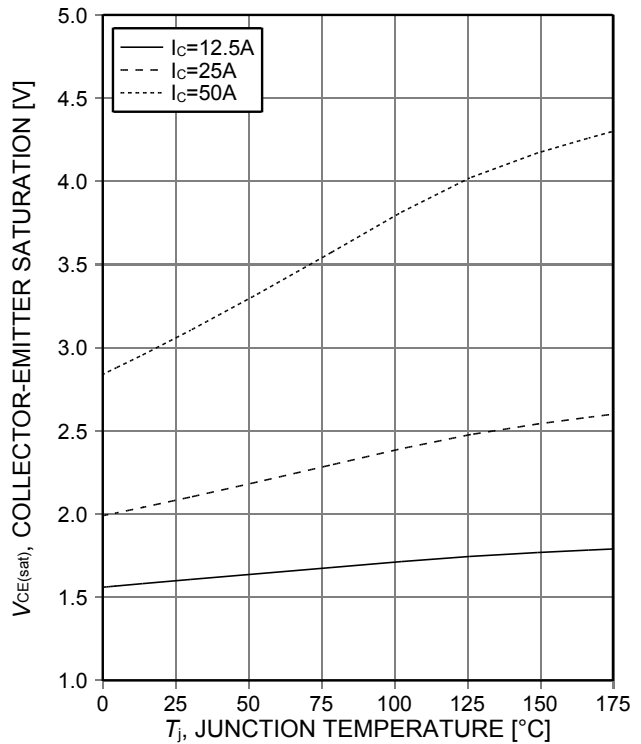


Figure 8. **Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE}=15\text{V}$ )



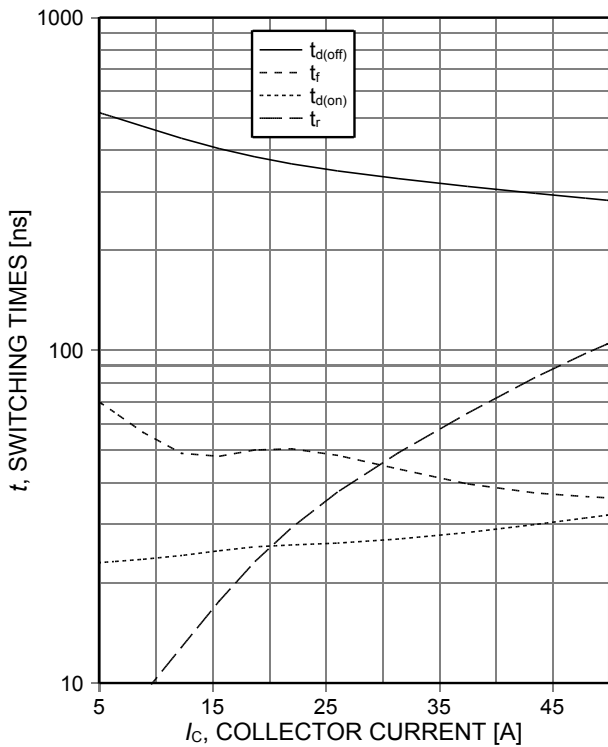


Figure 9. **Typical switching times as a function of collector current**  
 (ind. load,  $T_J=175^\circ\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $r_G=23\Omega$ , test circuit in Fig. E)

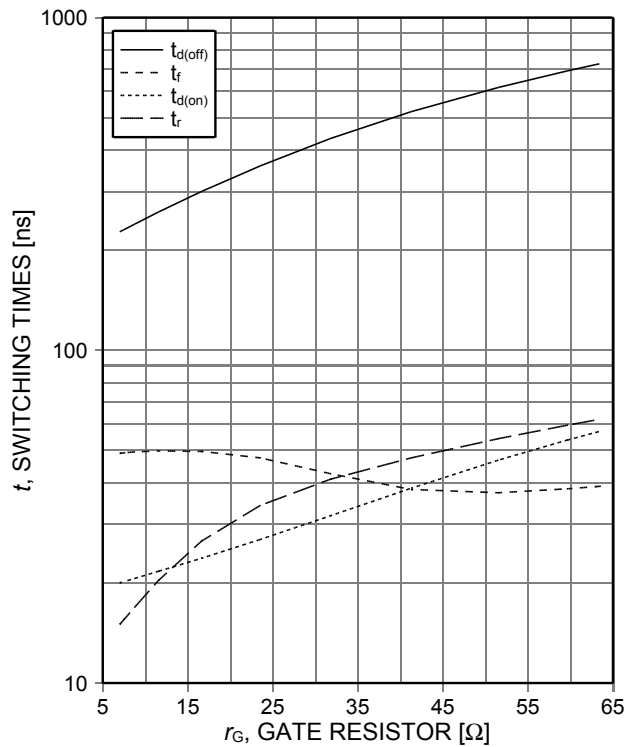


Figure 10. **Typical switching times as a function of gate resistor**  
 (ind. load,  $T_J=175^\circ\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=25\text{A}$ , test circuit in Fig. E)

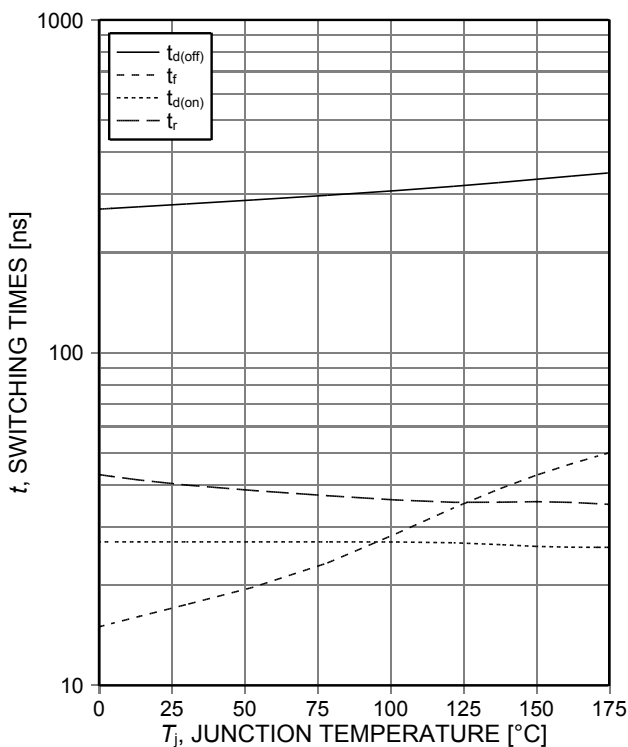


Figure 11. **Typical switching times as a function of junction temperature**  
 (ind. load,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=25\text{A}$ ,  $r_G=23\Omega$ , test circuit in Fig. E)

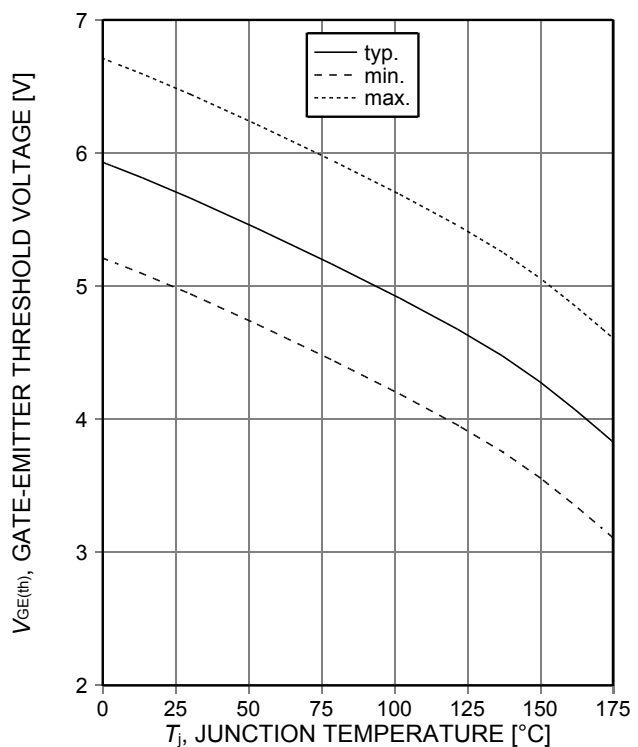


Figure 12. **Gate-emitter threshold voltage as a function of junction temperature**  
 ( $I_C=0.85\text{mA}$ )

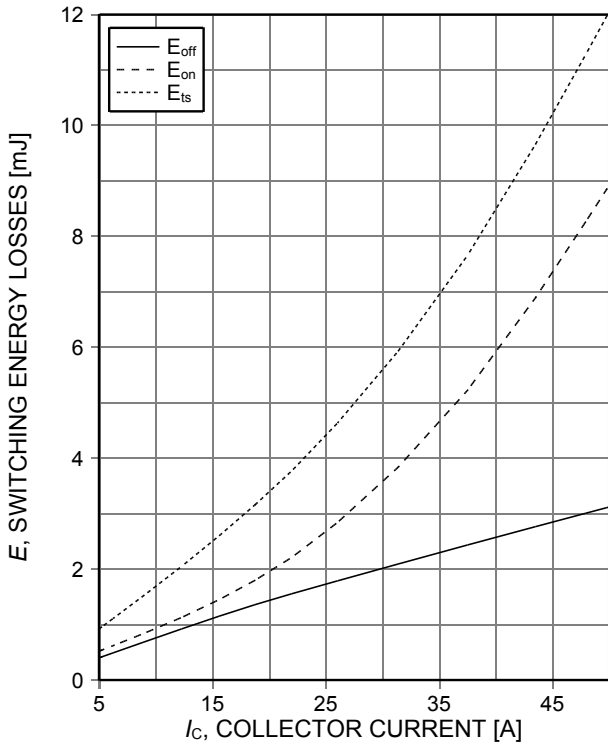


Figure 13. **Typical switching energy losses as a function of collector current**  
(ind. load,  $T_J=175^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $r_G=23\Omega$ , test circuit in Fig. E)

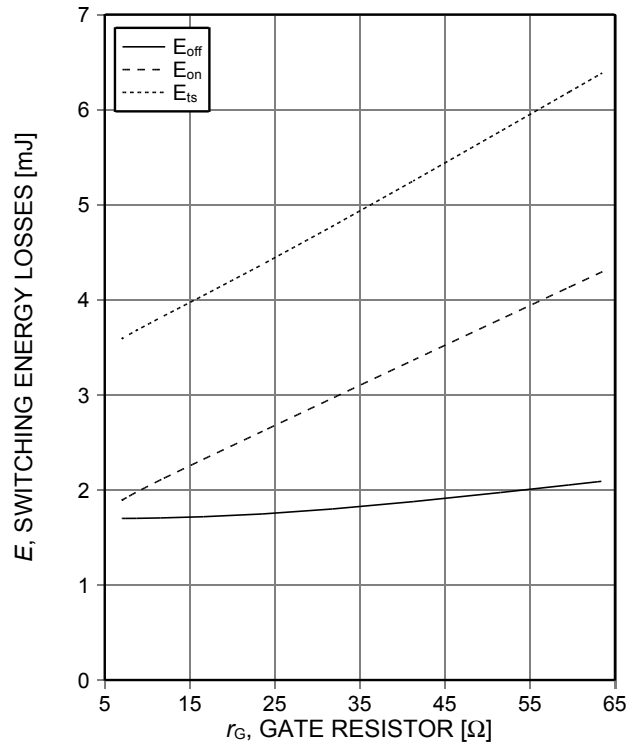


Figure 14. **Typical switching energy losses as a function of gate resistor**  
(ind. load,  $T_J=175^{\circ}\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=25\text{A}$ , test circuit in Fig. E)

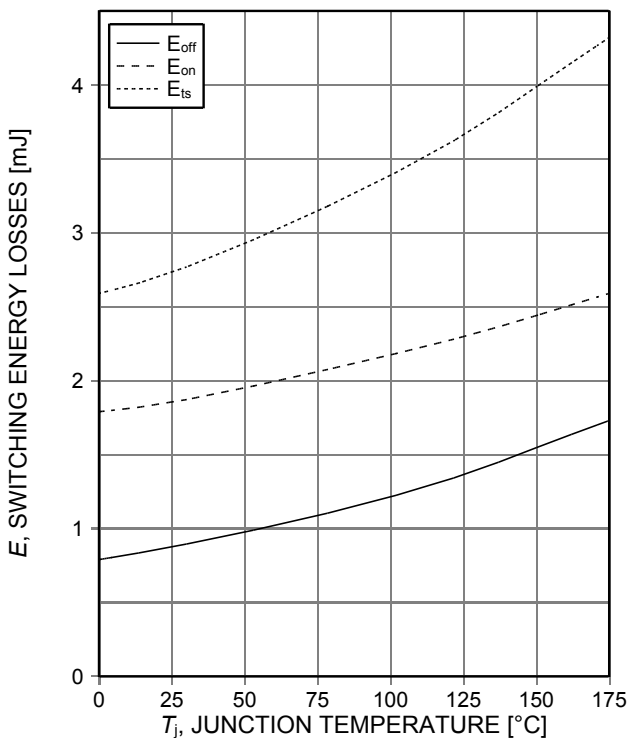


Figure 15. **Typical switching energy losses as a function of junction temperature**  
(ind load,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=25\text{A}$ ,  $r_G=23\Omega$ , test circuit in Fig. E)

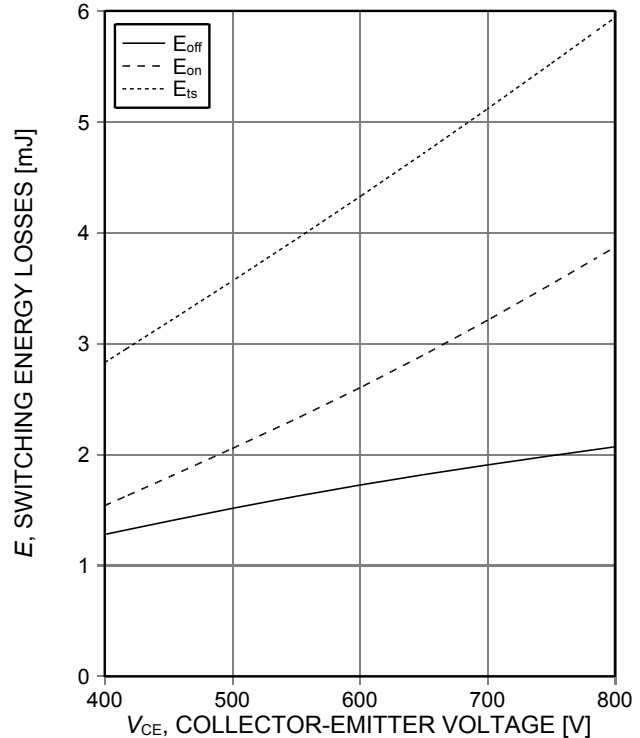


Figure 16. **Typical switching energy losses as a function of collector emitter voltage**  
(ind. load,  $T_J=175^{\circ}\text{C}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=25\text{A}$ ,  $r_G=23\Omega$ , test circuit in Fig. E)

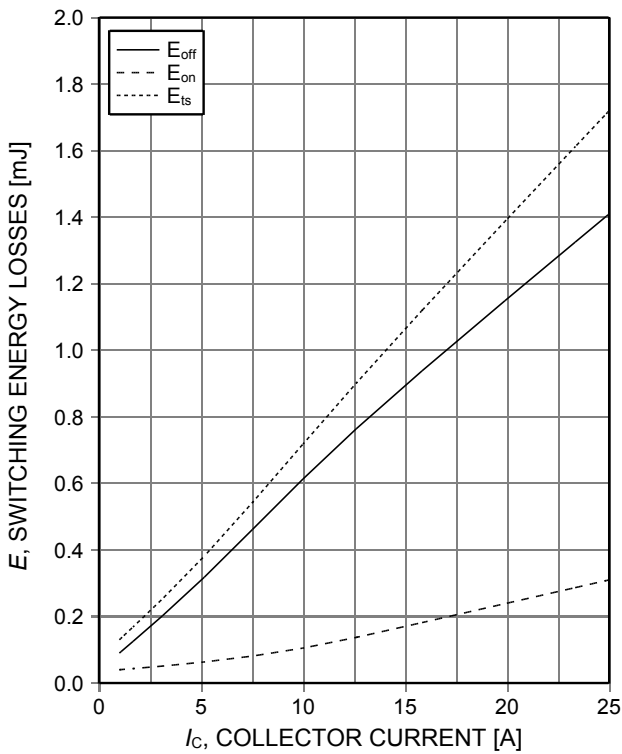


Figure 1. Typical switching energy losses as a function of collector current (ind. load,  $T_j=125^\circ\text{C}$ ,  $V_{CE}=800\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $r_G=3\Omega$ , Diode IDH15S120)

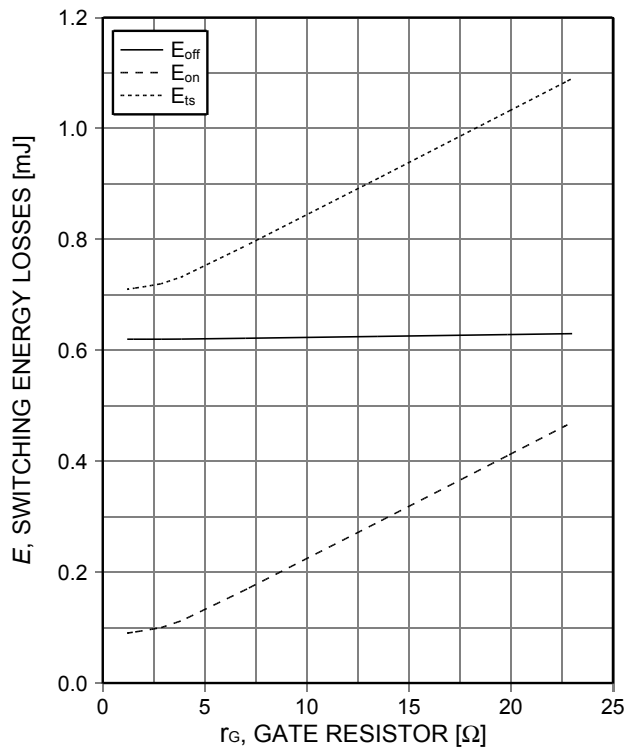


Figure 2. Typical switching energy losses as a function of gate resistor (ind. load,  $T_j=125^\circ\text{C}$ ,  $V_{CE}=800\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=10\text{A}$ , Diode IDH15S120)

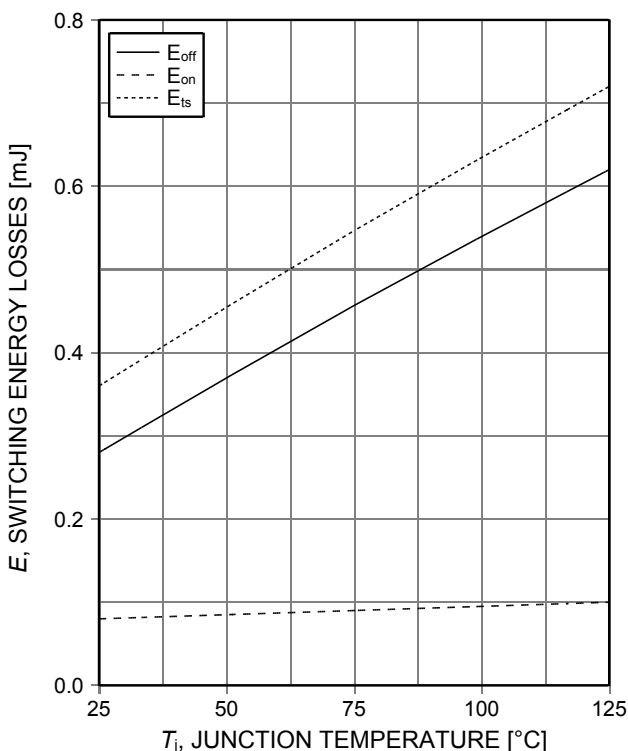


Figure 3. Typical switching energy losses as a function of junction temperature (ind. load,  $V_{CE}=800\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=10\text{A}$ ,  $r_G=3\Omega$ , Diode IDH15S120)

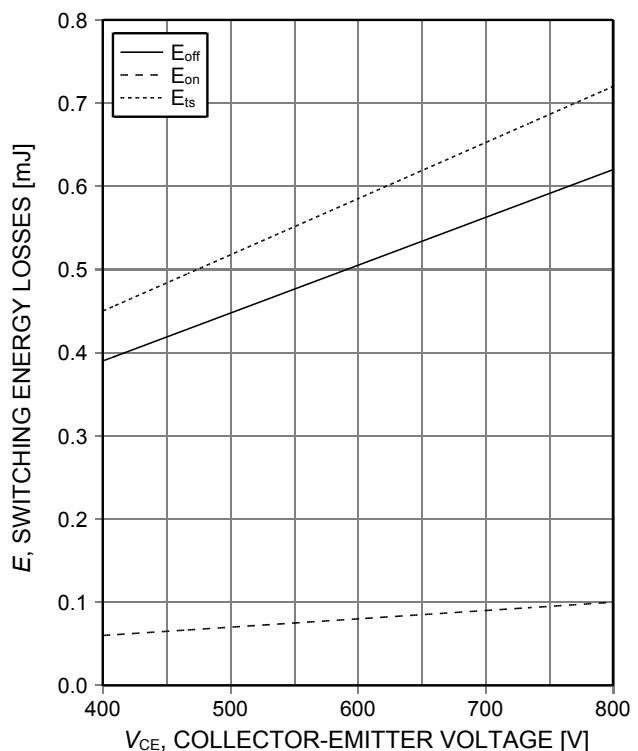


Figure 4. Typical switching energy losses as a function of collector emitter voltage (ind. load,  $T_j=125^\circ\text{C}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_C=10\text{A}$ ,  $r_G=3\Omega$ , Diode IDH15S120)

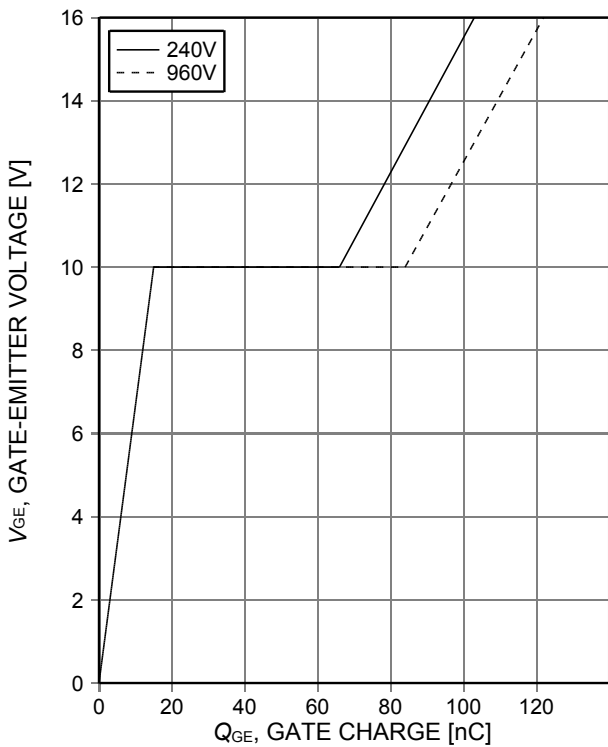


Figure 17. **Typical gate charge**  
( $I_C=25A$ )

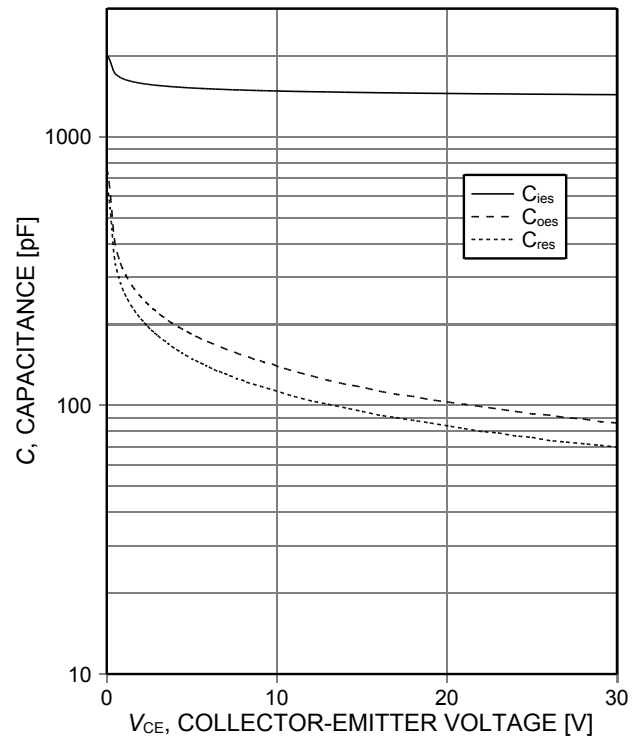


Figure 18. **Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE}=0V$ ,  $f=1MHz$ )

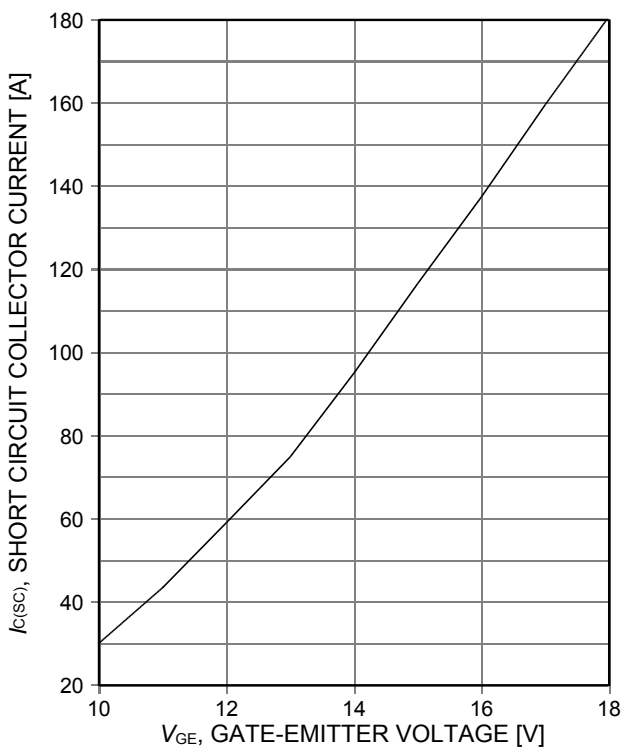


Figure 19. **Typical short circuit collector current as a function of gate-emitter voltage**  
( $V_{CE}\leq 600V$ , start at  $T_j=25^\circ C$ )

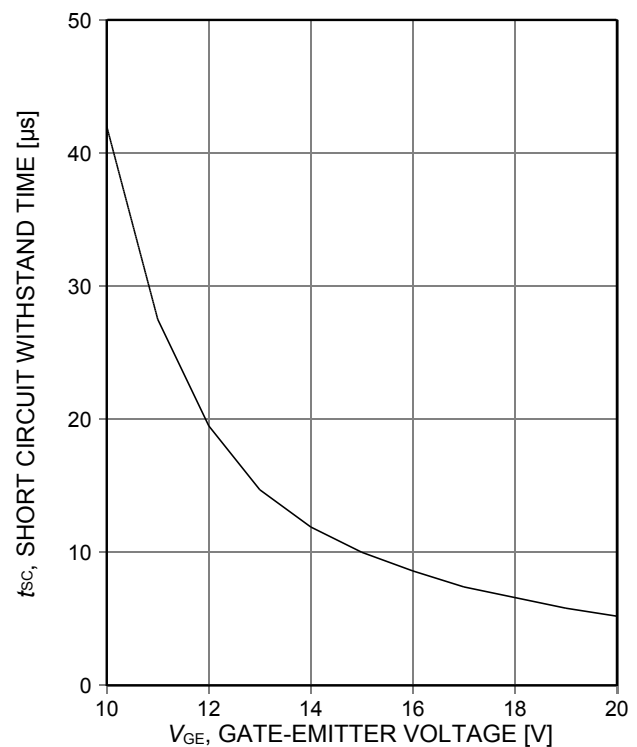


Figure 20. **Short circuit withstand time as a function of gate-emitter voltage**  
( $V_{CE}\leq 600V$ , start at  $T_j\leq 150^\circ C$ )

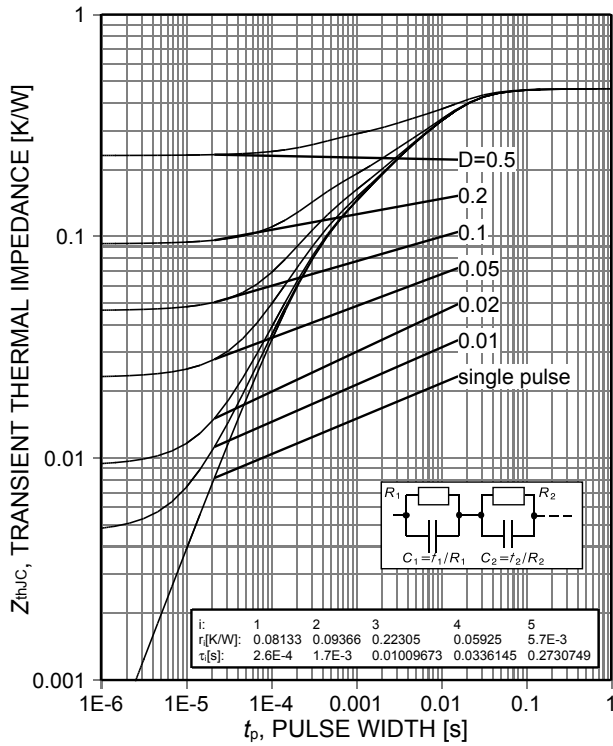
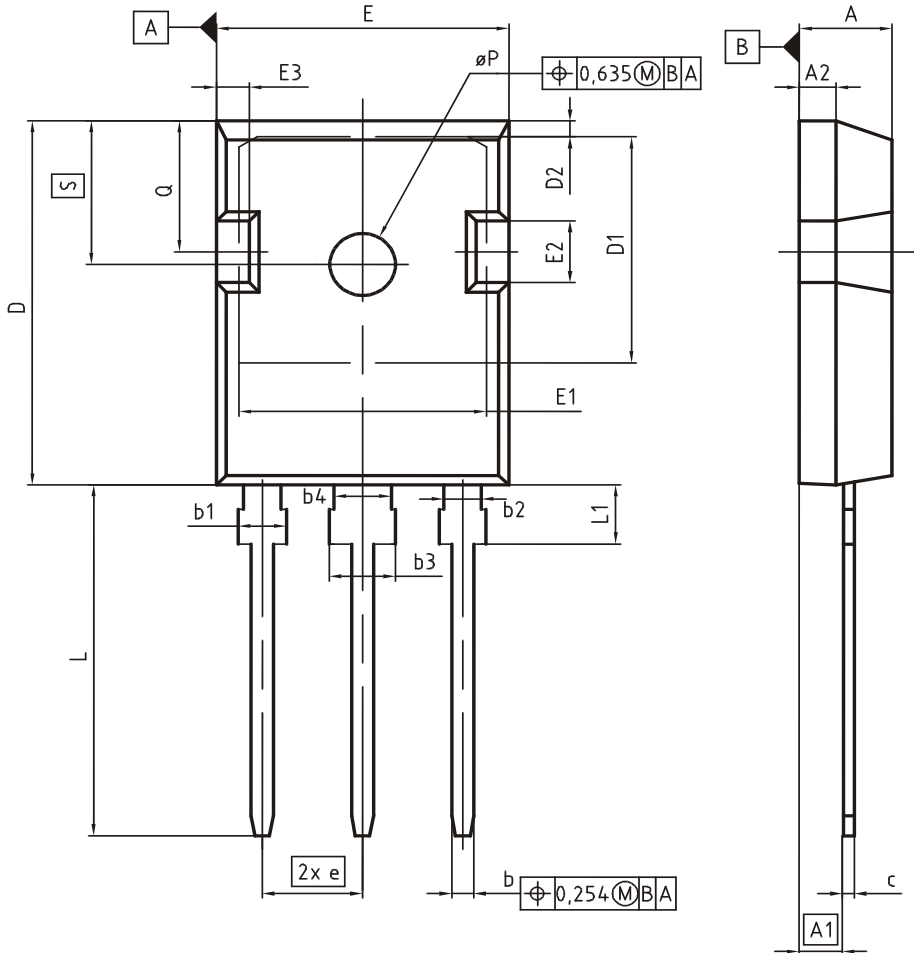


Figure 21. IGBT transient thermal impedance ( $D=t_p/T$ )

PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

DOCUMENT NO.  
Z8B00003327

SCALE

EUROPEAN PROJECTION

ISSUE DATE  
09-07-2010

REVISION  
05

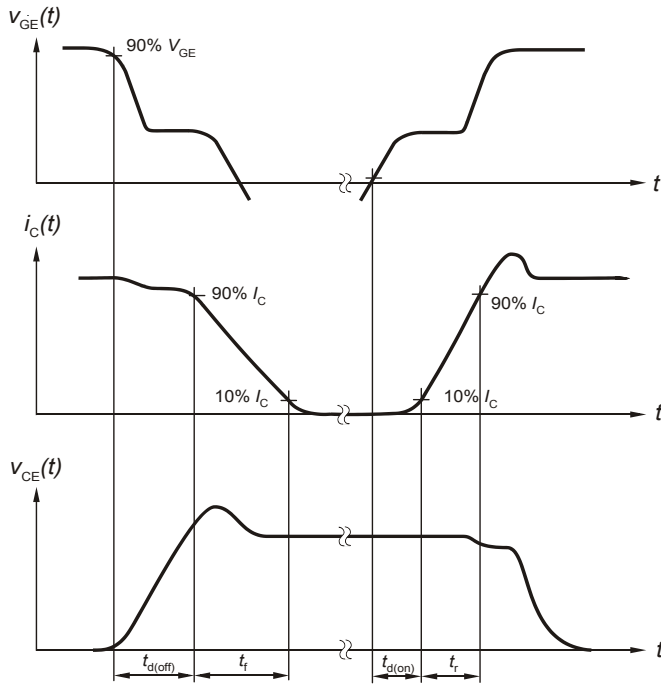


Figure A. Definition of switching times

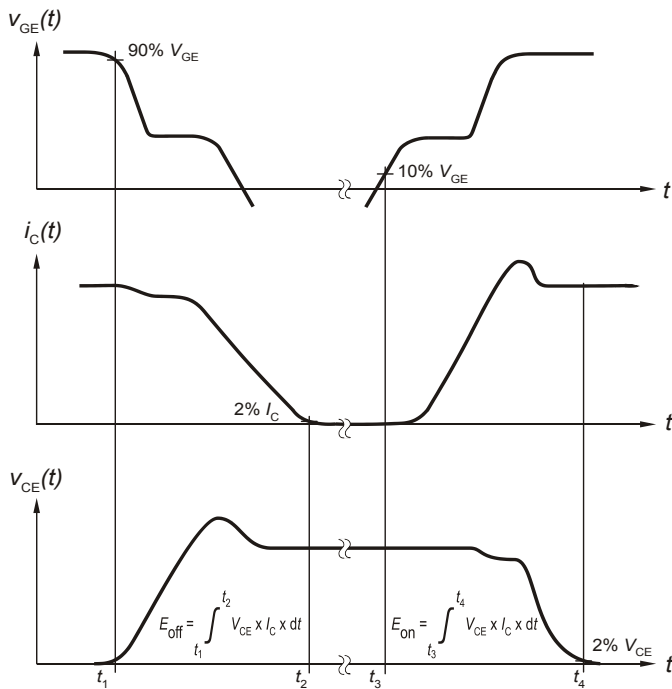


Figure B. Definition of switching losses

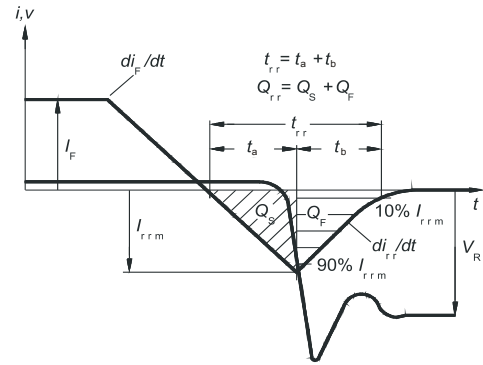


Figure C. Definition of diodes switching characteristics

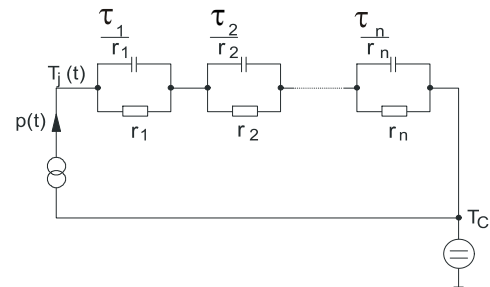


Figure D. Thermal equivalent circuit

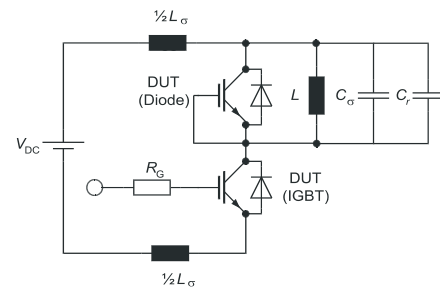


Figure E. Dynamic test circuit  
Parasitic inductance  $L_\sigma$ ,  
Parasitic capacitor  $C_\sigma$ ,  
Relief capacitor  $C_r$   
(only for ZVT switching)

**Revision History**

IGW25N120H3

**Revision: 2014-02-27, Rev. 2.1**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
1.1	2011-12-12	Preliminary data sheet
2.1	2014-02-27	Final data sheet

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Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

The Infineon Technologies component described in this Data Sheet may be used in life-support devices or systems and/or automotive, aviation and aerospace applications or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support, automotive, aviation and aerospace device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.



Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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